

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the Application.

Listing of Claims:

1. (Currently Amended) A viscosity reducible radiation curable composition comprising at least one radiation curable component, a thixotropic agent, a flow aid selected from the group consisting of ~~polyalkyleneoxide-modified~~ a polyalkyleneoxide-modified polydimethylsiloxane and an ethyl acrylate-2-ethylhexyl acrylate copolymer, and a filler, wherein the composition has the properties:

- i) a yield stress value of < 1100 Pa,
- ii) a viscosity (at a shear rate of 1 sec^{-1}) between 1 and 1500 Pa.sec, and
- iii) a filler settling speed less than 0.3 mm/day.

2. (Currently Amended) A viscosity reducible radiation curable composition comprising at least one radiation curable component, a thixotropic agent, a flow aid selected from the group consisting of ~~polyalkyleneoxide-modified~~ a polyalkyleneoxide-modified polydimethylsiloxane and an ethyl acrylate-2-ethylhexyl acrylate copolymer, and a filler, wherein the composition has the properties:

- i) a yield stress value of < 1100 Pa,
- ii) a viscosity (at a shear rate of 10 sec^{-1}) between 1 and 200 Pa.sec, and
- iii) a filler settling speed less than 0.3 mm/day.

3. (Previously Presented) The radiation curable composition according to claim 1, wherein the yield stress value is < 500 Pa.

4. (Previously Presented) The radiation curable composition according to claim 1, wherein the composition comprises at least one photoinitiator.

5. (Previously Presented) The radiation curable composition according to claim 1, wherein the composition has a thixotropic index of at least 3.

6-12. (Cancelled)

13. (Previously Presented) The radiation curable composition according to claim 1, wherein the composition comprises cationically curable components, and radically curable components.

14. (Previously Presented) The radiation curable composition according to claim 1, wherein the composition, relative to the total weight of the radiation curable composition, comprises between 30 and 90 wt% of cationically curable components.

15. (Previously Presented) The radiation curable composition according to claim 1, wherein the composition, relative to the total weight of the radiation curable composition, comprises between 5 and 50 wt% of radically polymerizable components.

16. (Currently Amended) A viscosity reducible radiation curable composition comprising, relative to the total weight of the radiation curable composition:

5-70 wt% of a difunctional epoxy compound ;

0.1-15 wt% of an acrylate having a functionality of larger than 2 ;

0.1-10 wt% of a thixotropic agent ;

0.01-5 wt% of a flow aid selected from the group consisting of polyalkyleneoxide modified a polyalkyleneoxide-modified polydimethylsiloxane and an ethyl acrylate-2-ethylhexyl acrylate copolymer;

10-90 wt% of a filler ; and

at least one photoinitiator .

17. (Original) The composition according to claim 16, wherein the composition has the properties:

- i) a yield stress value of < 1000 Pa,
- ii) a viscosity (at a shear rate of 1 sec^{-1}) between 0 and 1500 Pa.sec, and
- iii) a filler settling speed less than 0.3 mm/day.

18 -20. (Cancelled)

21. (Currently Amended) The composition according to claim 16, wherein the difunctional epoxy compound is selected from the group consisting of bisphenol A diglycidyl ether, bisphenol F diglycidyl ether, hydrogenated bisphenol A diglycidyl ether, hydrogenated bisphenol F diglycidyl ether, 3,4-epoxycyclohexylmethyl-3',4'-epoxycyclohexane carboxylate, bis(3,4-epoxycyclohexylmethyl)adipate, 1,4-butanediol diglycidyl ether, 1,6-hexanediol diglycidyl ether, polyethylene glycol diglycidyl ether, and polypropylene glycol diglycidyl ether.

22. (Previously Presented) The composition according to claim 16, wherein the acrylate having a functionality of larger than 2 is selected from the group consisting of trimethylolpropane tri(meth)acrylate, ethylene oxide-modified trimethylolpropane tri(meth)acrylate, dipentaerythritol hexa(meth)acrylate, dipentaerythritol penta(meth)acrylate, and ditrimethylolpropane tetra(meth)acrylate.

23. (Previously Presented) The composition according to claim 16, wherein the thixotropic agent is selected from the group consisting of polyvinylpyrrolidone, titanate coupling agents, aluminum distearate, aluminium tristearate, copolymers with acidic groups, fumed silica, organic derivatives of castor oil and polyoxyethylene-polyoxypropylene block copolymers.

24. (Currently Amended) The composition according to claim 16, wherein said composition further comprises one or more of the following components:

- A. ~~photosensitizers~~ a photosensitizer;
- B. a ~~reactive diluents~~ diluent;
- C. ~~resins~~ a resin;
- D. a ~~polymerization inhibitors~~ inhibitor;
- E. a ~~polymerization initiation-assistants~~ assistant;
- F. a ~~leveling agents~~ agent;
- G. a ~~wettability improvers~~ improver;
- H. ~~surfactants~~ a surfactant;
- I. ~~plasticizers~~ a plasticizer;
- J. a ~~UV absorbers~~ absorber;
- K. a ~~silane coupling agents~~ agent;
- L. ~~resin particles~~;
- M. ~~pigments~~ L. a pigment; and
- N. ~~dyes~~ M. a dye.

25. (Currently Amended) The composition according to claim 24 wherein component A is selected from the group consisting of amine compounds, thioxanethone and derivatives thereof, anthraquinone and derivatives thereof, anthracene and derivatives thereof, perylene and derivatives thereof, benzophenone, and benzoin isopropyl ether.

26. (Currently Amended) The composition according to claim 24, wherein component C is selected from the group consisting of epoxy resin, polyamide, polyamideimide, polyurethane, polybutadiene, polychloroprene, polyether, polyester, ~~styrene/butadiene-styrene~~ styrene/butadiene/styrene block copolymer, petroleum resin, xylene resin, ketone resin, cellulose resin, fluorine containing oligomer, and ~~silicon containing a silicon-containing oligomers~~ oligomer.